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Electronics manufacturing & assembly's Tape

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SHENZHEN KHJ TECHNOLOGY CO.,LTD
Add: KHJ industrial park, Building 1, Chuangxin industrial park, Xintian community
Guanlan, Longhua new district, Shenzhen, China.
Tel: +86-755-28102935 Fax: +86-755-82949800
E-mail: marketing@khj.cn, sales2@khj.cn
Web: www.khj.com.cn

Electronics manufacturing & assembly's Tape

Catalogue

–Industrial Adhesive Tapes

SHENZHEN KHJ TECHNOLOGY CO.,LTD



Electronic & Semiconductor Precise Processing
Adhesive Tapes Solution Provider

Company Profile





Shenzhen KHJ Technology Co.,Ltd was established in 1999 engaged in R&D, manufacturing and marketing of ESD adhesive products, with years experience in this field, KHJ has achieved a number of patents & core technology, we offer customized adhesive solution to meet customer's special requirements.

KHJ has cooperated with hundreds of electronic manufacturing factories worldwide for 20 years on the consumables for SMT/DIP production and electronic product assembly.

KHJ dedicated to become a global, innovative, responsible and public leader of ESD industrial adhesive tape.

Management Concepts



Mission:
Providing the best products and service for customers.

Vision:
Becoming the best partner with customers.

Core Values:
Human-people oriented.
Technology-knowledge innovation, technical innovation, management innovation.
Value-Bring profit to customers, create wealth to society.
Sharing-Together we share the responsibility and possession.
Devotion-Great enthusiasm to work, whole-hearted to give.
Responsibility-undertaking and devotion.

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Electronics manufacturing & assembly's Tape

Qualification & Certification

































Milestone

2023.04 Certified as a "Specialized, Sophisticated, and Innovative SME'"

2022.10 IATF16949:2016 Global Automotive Quality Management System cerfificated

2019.12 Intellectual property management system certificated

2017.04 Coatingwell function film R&D Center Founded

2016.11 National Hi-Tech enterprise awarded

2015.07 KHJ own industrial park builded

2013.08 The most innovative Award of China electronic equipment achieved

2011.05 Shenzhen Hi-Tech enterprise awarded

2009.10 Shenzhen KHJ Semiconductor Lighting Co.,Ltd Founded

2008.06 Zhuhai Office Founded

2008 Shenzhen KHJ Technology Co.,Ltd Founded

2006.12 ISO 14001 Certification awarded by Intertek

2003.04 ISO 9001 Certification awarded by Intertek

2002.12 Decai Printing Co.,Ltd Founded

2001.08 Shanghai Brach Founded

1999.10 Shenzhen KHJ Electronics Co.,Ltd Founded









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• Polyimide film Tape

Description

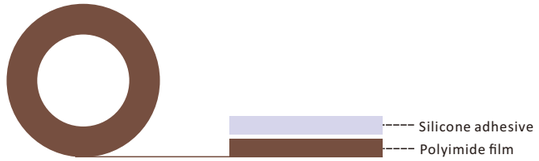
Polyimide film tape is a polyimide film backed silicone adhesive,used for PCB solder masking and other high-temperature applications .



Features

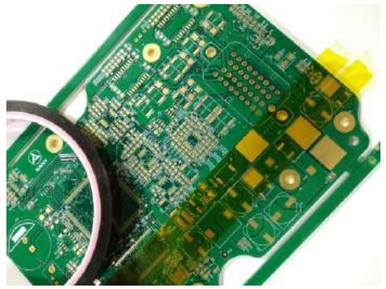
- ●Excellent performance in electrical and thermal insulation and have high dielectric strength (Breakdown voltage＞4KV);
- ●Clean removal without any residue after high-temp process;
- ●Low antistatic ,surface resistance is 10^5-10^{10}ohms;
- ●Halogen free RoHS Compliant.

Construction



Application

- ●Environment where static discharge is a concern;
- ●High temperature masking;
- ●Insulation on Transformers, Motors and Coils ;
- ●Protection of circuit board gold finger contacts during wave solder.



Typical Physical Properties

Part No.	Backing	Adhesive	Total thickness (um)	Adhesion to steel (N/25mm)	ESD	Temperature Resistance (℃)	Color
E1-IH803 Series	PI	Silicone	45	3	Surface Resistance	280	Amber
E1-IH807J	PI	Silicone	90	3-4	Surface Resistance	270	Amber
E1-IH826	PI	Silicone	55	4	Surface Resistance	260	Black
E2-IH823C	PI	Silicone	55	4	Surface Resistance	280	Black
IH852 Series	PI	Silicone	55	4	N/A	280	Amber
IH852TP	PI	Silicone	45	2.5	N/A	280	Amber

The above technical information and data should be considered representative or typical only and should not be used for specification purposes.

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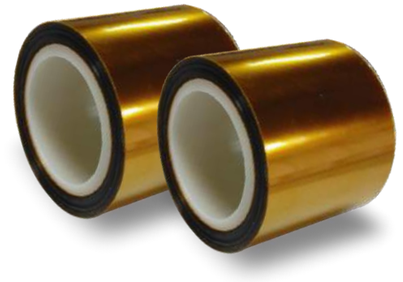
• Non-Silicione Polyimide Film Tape

Description

The non-silicone high temperature resistant tape is based on Polyimide film and coated with special non-silicone pressure-sensitive adhesive on the surface, which can meet the production process of specific requirements, especially suitable for electronic production with high restrictions on silicone contamination.

Features

- ●Excellent high-temp resistance with not residue after removal;
- ●Non-silicone adhesive formulation helps eliminate the potential silicone contamination which can interfere with subsequent bonding or conformal-coating operations;
- ●Good initial viscosity easy for instant bonding.



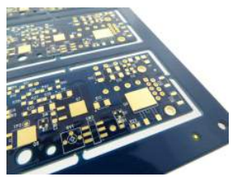
Application

- ●It is used in the SMT field with high bonding requirements, such as automotive and aviation electronics control system, laser radar and optical telecommunication moduleSemiconductor packaging process, lead frame protection, prevent resin leakage.

Construction



Automotive Electronics





Optical Communication





Typical Physical Properties

Part No.	Backing	Adheisve	Total thickness (um)	Adhesion to steel (N/25mm)	ESD	Temperature Resistance (℃)	Color
IH890PN	PI	Acrylic adhesive	42	1.8-3.5	N/A	260℃*10min	Amber
IH899BF	PI	Acrylic adhesive	42	0.5-1.5	N/A	200℃*2H	Amber
IH899AG	PI	Acrylic adhesive	42	1-2.2	Surface Resistance	260℃*10min	Amber

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• Double Side Coated Polyimide Film Tape

Description

Double side coated Polyimide Tapes are made of Polyimide film with silicone adhesive coating on both sides,it has excellent properties of instant sticking,high-temp resistance,Acid-base resistance and no residual after removal.

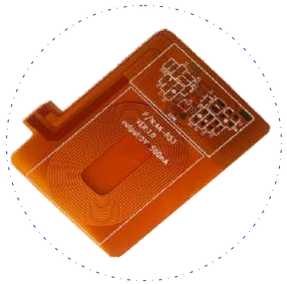
Features

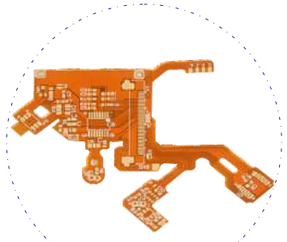
- ●Different adhesion on both-sides available to stick two different material's surface ;
- ●Withstand high temperature up to to260℃ and no adhesive residual afer removal;
- ●Available with easily removable inter-liner.



Application

- ●Used for fixing FPC on jig during SMT and flip chip process;
- ●Masking for printed circuit boards during wave solder or solder dip process.





Construction



Typical Physical Properties

Part No.	Backing	Adheisve	Total thickness (um)	Adhesion to steel (N/25mm)	ESD	Temperature Resistance (℃)	Color
DIH772A-B	PI	Silicone	85	A:6 ; B:4	N/A	260	Amber
DIH775A-B	PI	Silicone	200	A:8 ; B:0.8	N/A	260	Amber
E2-DIH776A-B	PI	Silicone	205	A:6.5 ; B:1	Surface & Adhesive Resistance	260	Black

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• Polyester Masking Tape

Description

Polyester Masking Tapes, also known as Powder Coating Masking Tapes, are made of polyester film with silicone adhesive. They can withstand temperatures of up to 200°C. Polyester Masking Tapes are extremely economical and can be removed cleanly without leaving any adhesive residue.

Features

- ●Heat resistant up to 200°Cfor 20 minutes;
- ●Removes cleanly even after long bake cycles with not residue;
- ●Low antistatic ,surface resistance is 10^5-10^{10} ohms;
- ●Halogen free RoHS Compliant.

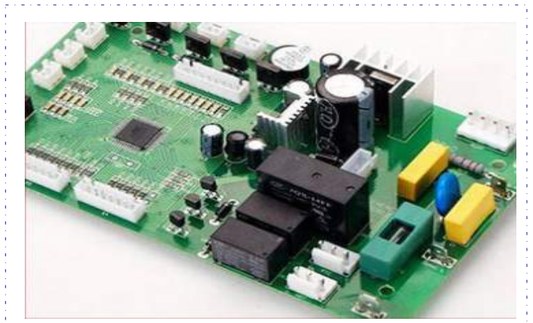


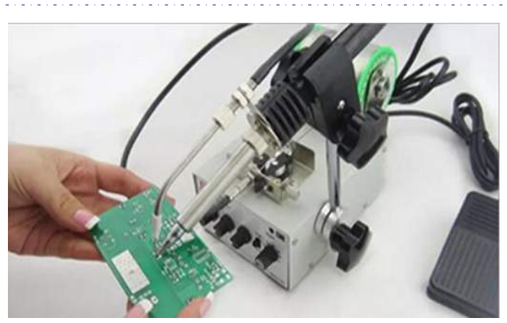
Application

- ●Excellent for general purpose masking during powder coating, painting, anodizing , etc;
- ●Masking electronic components during electronic high temperature processing.

Construction







Typical Physical Properties

Part No.	Backing	Adhesive	Total thickness (um)	Adhesion to steel (N/25mm)	ESD	Temperature Resistance (℃)	Color
TH865G	PET	Silicone	80	8-10	N/A	220	Light Green
E1-TH862G	PET	Silicone	60	5-7	Surface Resistance	200	Green transparent

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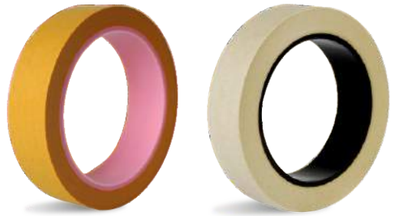
• Paper Masking Tape

Description

Masking Tape is a high Performance, excellent paint masking tape for holding, protecting, bundling and more. Constructed with a washi paper or crepe paper backing, this masking tape has instant adhesion and excellent holding power to make sure tear easily from the roll by hand, sticks confidently, and can be removed conveniently and quickly. Antistatic types are available.

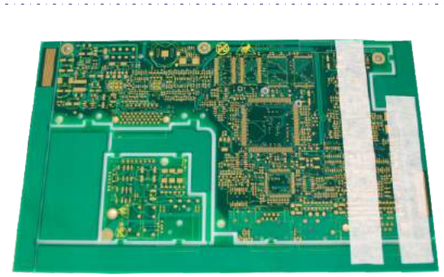
Features



- ●Adheres well to a variety of substrates ;
- ●Clean removal from most surfaces;
- ●Highly conformable and easy unwind;
- ●Easy tear & No stretching.

Application

- ●Masking the surface during spray painting, power coating and electroplating;
- ●Labeling and attaching;
- ●Ideal for marking, temporary holding, wrapping and sealing.



Construction



Typical Physical Properties

Part No.	Backing	Adhesive	Total thickness (um)	Adhesion to steel (N/25mm)	ESD	Resistance Value	Temperature Resistance (℃)	Color
E1-MH310G	Crepe Paper	Silicone	140	6	Surface Resistance	$10^{6-10}\Omega$	200	White
E2-MA311	Crepe Paper	Acrylic	110	5	Surface & Adhesive Resistance	Surface: $10^{6-11}\Omega$ Adhesive: $10^{6-11}\Omega$	NO	White
E1-MH306	Crepe Paper	Acrylic	85	4	Surface Resistance	$10^{6-10}\Omega$	200	Yellow

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• Thermal Release Tape

Description

The thermal release tape is a polyester film backed unique adhesive tape. It's adhesion equivalent to a normal adhesive tape at room temperature but can be easily peeled off when heating. There are two types: Single-sided and double-sided.

Features



- ● High adhesion at room temperature;
- ● Adhesion disappear when heat when heating;
- ● No residue and damage to substrate when removing tape.

Application

- ●Surface protection during dicing, grinding and polishing of PCB, ceramic,MLCC, glass, wafer, LCD and LED etc;
- ●Surface protection during metal housing secondary anodized processing;
- ●Surface protection during copper substrate solution immersion processing.

Construction





Typical Physical Properties

Part No.	Backing	Adhesive	Total thickness (um)	Adhesion to steel before Heating (gf/25mm)	Releasing Temperature (℃)	Releasing Time (min)	Adhesion to steel after Heating (gf/25mm)
TS600D	PET	Acrylic	155	1000	105-130	3-10	0
TS650RN	PET	Acrylic	150	700	110-135	3-10	0
TS652D	PET	Acrylic	150	800	110-135	3-10	0
DTS640A	PET	Acrylic	200	700	125-135	3-10	0
TS658M	PET	Acrylic	140	2500	150-160	3-10	0
TS651ZF	PET	Acrylic	155	500	150-160	3-10	0

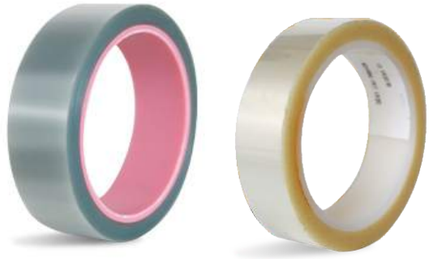
The above technical information and data should be considered representative or typical only and should not be used for specification purposes.

• UV Release Tape

Description

UV Release Tape is a kind of anti-static ultraviolet tape, with high initial adhesion, after UV irradiating ,adhesion is greatlly decreaed or losed and no adhesive residual after remoal.

Features



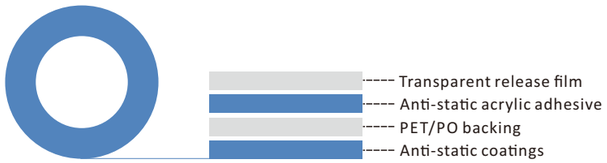
- Excellent anti-static performance.
- High initial adhesion strength, easy removal of component after UV irradiating, no adhesive residual.
- The adhesive layer counteracts the force of slicing and protects the components.

Application

- It can be used for surface protection of cutting and positioning of various silicone packages, components, ceramic capacitors and PCB boards.



Construction



Typical Physical Properties

Part No.	Backing	Adhesive	Backing thickness (um)	Total thickness (um)	Adhesion to steel (gf/25mm) *		
					Before UV	Initional adhesion	After UV
UV408T	PO	Acrylic	150	160	1200	■■■■	< 10
UV408H	PO	Acrylic	150	170	1500	■■■■	< 10
UV406F	PO	Acrylic	150	170	1200	■■■	< 10
UV391PY	PO	Acrylic	150	170	2500	■■	< 10
E1-UV391A	PO	Acrylic	150	170	2500	■■	< 10
UV390WR	PO	Acrylic	70	90	2000	■■	< 10
UV402DW	PO	Acrylic	80	90	800	■■	< 10
UV396US	PET	Acrylic	100	120	3000	■■	< 10

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• Semiconductor Packaging Tape

Description

Semiconductor packaging protective tape with excellent adhesion performance and high temperature resistance which is used for the fixed protection of semiconductor chip packaging with not adhesive residue after removal.

Features



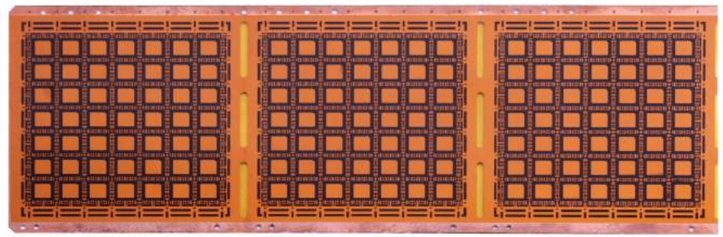
- Material and coating uniform, high precision;
- Basic PI film with excellent high temperature resistance and good thermal stability;
- No need to preheat when sticking and peeling the tape;
- With not adhesive residue after removal;
- High cleanliness, no stains and impurities;
- ESD performance can be added for high-end requirements.

Application

- The packaging process of semiconductor chips such as QFN;
- Used to fix the lead frame and prevent the leakage of epoxy resin;
- High temperature protection, temporary fixation, masking;
- Processes that require precise protection, such as chips and films.

Construction





Typical Physical Properties

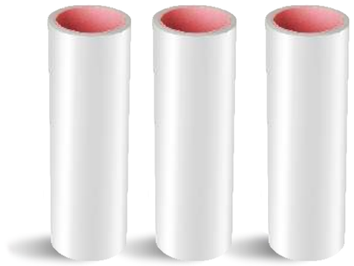
Part No.	Backing	Adhesive	Total thickness (um)	Adhesion to steel (N/25mm)	Temperature Resistance (℃)	Color
IH869CP	PI	Silicone	31	0.7	260	Amber
IH812FD	PI	Silicone	35	3.5	260	Amber

The above technical information and data should be considered representative or typical only and should not be used for specification purposes.

• Anti-static Sticky Rolls

Description

The sticky roll is made of white PP synthetic paper as the base material, with a special acrylic adhesive coated on the surface. ,It with good dust cleaning, excellent anti-static performance and no adhesive residual.



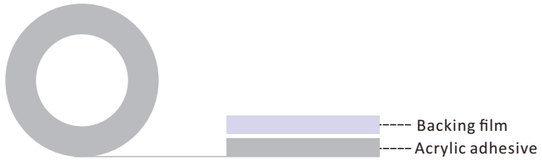
Features

- ●Good Viscosity, no adhesive degumming when peeling;
- ●Cutter line design, easy to use;
- ●Unwinding voltage meet anti-static level.

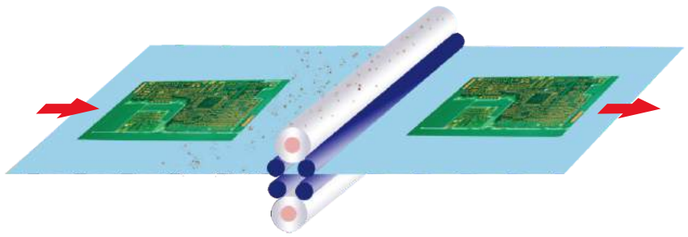
Application

- ●Specially work in PCB cleaning machine and as well as antistatic dust removal of membrane materials and flat materials in a dust-free environment.

Construction







Typical Physical Properties

Part No.	Backing	Adhesive	Total thickness (um)	Adhesion to steel (N/25mm)	ESD	Resistance Value	Color
E2-IC168	PP	Acrylic	90	2 - 3	Surface & Adhesive Resistance	$10^{6-11}\Omega$	Milky white
E2-IC268A	PP	Acrylic	85	1	Surface & Adhesive Resistance	$10^{6-11}\Omega$	Milky white

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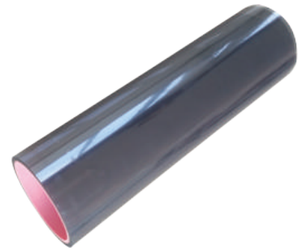
• Trial Solder Paste Printing Film

Description

This Film is polyester based and coated with acrylic adhesive. It has good features of anti-static and low viscosity without residue after removal.

Features

- ● High cleanliness, good transparency and no pollution;
- ● Using PET film, easy to die-cut;
- ● High-performance acrylic glue, no glue powder, no glue residue;
- ● It can be operated repeatedly, easy to stick and peel.



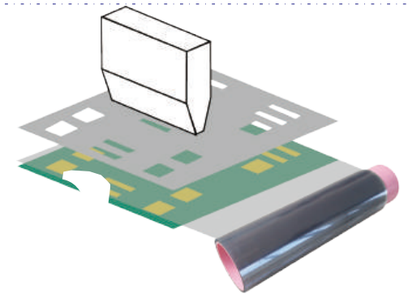
Application

- ● Checking solder paste print quality and accuracy in the solder paste trial printing stage;
- ● Die-cutting protection for various products;
- ● Surface protection of various instruments, equipment and other products.

Constructure







Typical Physical Properties

Part No.	Backing	Adhesive	Total thickness (um)	Adhesion to steel (N/25mm)	ESD	Color
E2-AF123E	PET	Acrylic	45	1-3.5	Surface & Adhesive Resistance	Gray-Tansparent

The above technical information and data should be considered representative or typical only and should not be used for specification purposes.

• ESD Packing Tape

Description

This kind of tape is polyester aluminum metalized or pure polyester based and coated with acrylic adhesive tapes. It is characterized by high-adhesion, super anti-static (ESD) properties and no residue after removal.

Features

- ●Excellent adhesion and cohesion;
- ●Easy sticking on different surface;
- ●Stable properties No residue after removal;
- ●Anti-static resistance:10^5-10^{10} ohms.



Application

- ● ESD bag sealing, packing and components fixing, accessories bulding.

Constructure





Typical Physical Properties

Part No.	Backing	Adhesive	Total thickness (um)	Adhesion to steel (N/25mm)	ESD	Color
E1-FA921B	PET	Acrylic	45	＞15	Surface Resistance	Transparent
E2-FA926S	PET	Acrylic	55	≥6	Surface & Adhesive Resistance	Silver

The above technical information and data should be considered representative or typical only and should not be used for specification purposes.

• ESD SMT Splice tape



Since from 1999, KHJ was dedicated in development of the SMT/AI splicing products,and keep on innovation about adhesive strength & holding power,anti-static,conductive,speical performance,and structure for our products. Currently,our single splice tape,double splice tape,universal splice tape and speical splice tape are widely used in the SMT industry,we are always striving to provide customers with unexpected value,and superior quality products with high cost performance.

Products Features:

1) Applicable in jointing SMD carrier tapes to ensure a non-stop production for different SMT machines.
2) Four type of splice tape series: Double splice tape,single splice tape,universal splice tape,and speical splice tape.
3)Easy operation,labor saving,and high efficiency.
4)Excellent & reliable jointing with high accuracy and high cost performance.

Remark:

1) Available colors of SMT splice tape: yellow,light yellow,transparent yellow,blue,gloosy black,matte black,light green,pink and silver.
2) Different colors are used to be detectable by feeder,striking, and distinguishable for different components.
Color code: Yellow(C),Blue(N),glossy black(G),matte black(M),light green(L).
3) X stands for bevel shape of splice tape.
4) Storage period:1/2~1 year,storage condition: under room temperature 10~30°C.

• ESD SMT Splice tape

SMT double splice tape (01 Series)

Product image	Description	P/N	Application	Qty	Color	ESD	NO ESD
	Double splice tape	SMS0108/12/16/24	For 8mm/12mm/16mm/ 24mm carrier tape (Emboss)	500/250Pcs/Box	C	√	√
					N	√	√
					G	√	√
					M	√	√
					L	√	√

Application: Available for all SMT machines(Except sensitive machine).

SMT single splice tape(03 Series)

Product image	Description	P/N	Application	Qty	Color	ESD	NO ESD
	Single splice tape	SMS0308/12/16/24/ 32/44/56	For 8mm/12mm/16mm/ 24mm/32mm/44mm/ 56mm carrier tape (Emboss)	4000/2000/1000 Pcs/Box	C	√	√
					N	√	√
					G	√	√
					M	√	√
					L	√	√

Application: Available for all SMT machines(Except sensitive machine).

SMT splice tape with clip(08 Series)

Product image	Description	P/N	Application	Qty	Color	ESD	NO ESD
	Universal splice tape	SMS0808/12/16/24	For 8mm/12mm/16mm/ 24mm carrier tape (Emboss)	500/250Pcs/Box	C	√	√
					N	√	√
					G	√	√
					M	√	√
					L	√	√

Application: Available for all SMT machines(Except sensitive machine).

SMT special splice tape (09 Series)

Product image	Description	P/N	Application	Qty	Color	ESD	NO ESD
	Special splice tape	SMS0908/12/16/24	For 8mm/12mm/16mm/ 24mm carrier tape (Emboss)	500/250Pcs/Box	C	√	√
					N	√	√
					G	√	√
					M	√	√
					L	√	√

Application: Used for Universal, Juki, Sanyo, Hitachi machine.

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Electronics manufacturing & assembly's Tape

• ESD SMT Splice tape

SMT splice cover tape extender (11 Series)

Product image	Description	P/N	Application	Qty	Color	ESD	NO ESD
	SMT Cover tape extender	SMS1108/12/16/24/32	For 8mm/12mm/16mm/ 24mm/32mm carrier tape (Emboss)	500/250Pcs/Box	C	√	√
					N	√	√
					G	√	√
					M	√	√
					L	√	√

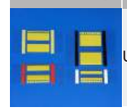
Application: Available for all SMT machines.

SMT special splice tape (13 Series)

Product image	Description	P/N	Application	Qty	Color	ESD	NO ESD
	Special splice tape	SMS1308/12/16/24	For 8mm/12mm/16mm/ 24mm carrier tape (Emboss)	500/250Pcs/Box	G	√	√
					M	√	√

Application: Applicable for Hitachi ,Panasonic Cm402.

SMT splice tape with holes (15 Series)

Product image	Description	P/N	Application	Qty	Color	ESD	NO ESD
	Universal splice tape	SMS1508/12/16/24/ 32/44	For 8mm/12mm/16mm/ 24mm/32mm/44mm carrier tape (Emboss)	500/250Pcs/Box	C	√	√
					N	√	√
					G	√	√
					M	√	√
					L	√	√

Application: Various machine applicable.

SMT special splice tape with clips (16 Series)

Product image	Description	P/N	Application	Qty	Color	ESD	NO ESD
	Special splice tape & clips	SMS1608/12/16/24/32	For 8mm/12mm/16mm/ 24mm/32mm carrier tape (Emboss)	500/250Pcs/Box	G	√	√
					M	√	√

Application: Sense by metal or color, ideal Panasonic, Siemens, Fuji Machine.

• ESD SMT Splice tape

SMT single splice tape with alignment guide 17 Seires)

Product image	Description	P/N	Application	Qty	Color	ESD	NO ESD
	single splice tape with alignment guide	SMS1708/12/16/24	For 8mm/12mm/16mm/ 24mm carrier tape (Emboss)	1000Pcs/Box	C	√	√
					N	√	√
					G	√	√
					M	√	√
					L	√	√

Application: Available for all SMT machines(Except sensitive machine).

SMT double splice tape with alignment guide (18 Series)

Product image	Description	P/N	Application	Qty	Color	ESD	NO ESD
	Double splice tape with alignment guide	SMS1808/12/16/24	For 8mm/12mm/16mm/ 24mm carrier tape (Emboss)	500/250Pcs/Box	C	√	√
					N	√	√
					G	√	√
					M	√	√
					L	√	√

Application: Available for all SMT machines(Except sensitive machine).

SMT special splice tape (19 Series)

Product image	Description	P/N	Application	Qty	Color	ESD	NO ESD
	Special splice tape	SMS1908	For 8mm carrier tape (Emboss)	500Pcs/Box	C	√	√
					N	√	√
					G	√	√
					M	√	√
					L	√	√

Application: Applicable for Universal, Juki, Sanyo, Hitachi Machines.

SMT special splice tape (20 Series)

Product image	Description	P/N	Application	Qty	Color	ESD	NO ESD
	Special splice tape	SMS2008	For 8mm carrier tape (Emboss)	500Pcs/Box	C	√	√
					N	√	√
					G	√	√
					M	√	√
					L	√	√

Application: Applicable for Univeral, Juki, Sanyo, Hitachi machines.

The above technical information and data should be considered representative or typical only and should not be used for specification purposes.

• ESD SMT Splice tape

SMT single splice tape (21 series)

Product image	Description	P/N	Application	Qty	Color	ESD	NO ESD
	Single special splice tape	SMS2104C	For 4mm carrier tape (Emboss)	500Pcs/Box	C	√	√
					N	√	√
					G	√	√
					M	√	√
					L	√	√

Application: For jointing 4mm carrier tape only.

SMT special splice tape (25 Series)

Product image	Description	P/N	Application	Qty	Color	ESD	NO ESD
	Special splice tape	SMS2508/12/16/24/ 32/44	For 8mm/12mm/16mm/ 24mm/32mm/44mm carrier tape (Emboss)	500/250Pcs/Box	G	√	√
					M	√	√
					L	√	√

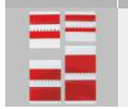
Application: Color sense, applicable for KME.

SMT special splice tape for Fuji (27 Series)

Product image	Description	P/N	Application	Qty	Color	ESD	NO ESD
	Special splice tape	SMS2704/08/12/16/24	For 4mm/8mm/12mm/ 16mm/24mm carrier tape (Emboss)	500/250Pcs/Box	R	√	√
					F	√	√

Application: Applicable for Fuji NXT, Siemens.

SMT special splice tape for ASM (29 Series)

Product image	Description	P/N	Application	Qty	Color	ESD	NO ESD
	Special splice tape	SMS2904/08/12/16/24	For 4mm/8mm/12mm/ 16mm/24mm carrier tape (Emboss)	500/250Pcs/Box	R	√	√
					F	√	√

Application:

- Applicable for ASM.

Remark:Holes alignment for precise jointing;
Metal or color sense available.

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• ESD SMT Splice tape

SMT special splice tape for Panasonic (35 Series)

Product image	Description	P/N	Application	Qty	Color	ESD	NO ESD
	Special splice tape	SMS3508/12/16/24	For 8mm/12mm/16mm/ 24mm carrier tape (Emboss)	500/250Pcs/Box	G	√	√
					M	√	√

Application:

●SMT special splice tape for Panasonic;
Remark:Two guides design for precise jointing.

SMT special splice tape for Automatic splicing (36 Series)

Product image	Description	P/N	Application	Qty	Color	ESD	NO ESD
	Special splice tape	SMS3608X	For 8mm carrier tape (Emboss)	1200/3000Pcs/Box	C	√	√
					G	√	√
					R	√	√
					F	√	√

Application:

●Ideal for automatic splicing machine, high jointing efficiency;
Remark:Metal sense to avoid wrong components jointing.

SMT Carrier Tape End Sealer Label

Product image	Description	P/N	Application	Qty	Surface Resistance	Static Voltage	Core ID
	SMT Carrier Tape End Sealer Label	SMS4001C - T	It is used for fixing and sealing the end of SMT carrier tape reels or other materials reels.	3000pcs/roll	10^{5}-$^{10}\Omega$	< 100V	38mm

●ESD with no damage to electronics components.
●Two end with no adhesive,easy to peel and pull.
●The green non-adhesive area is a clear mark which can be identified effectively to peel off this label from reels at correct direction to avoid peel the cover tape off.

Using demo:







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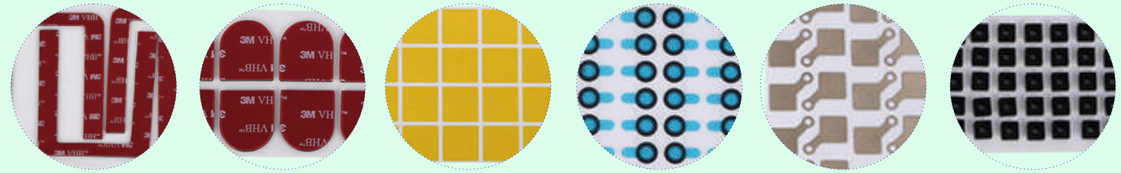
• Precise Die-Cutting



We provide all kinds of customized precision die-cutting products for well-known enterprises in the electronic communication industry, including adhesive products, protective films, gaskets, shock absorbers, etc. Shielding insulators, dust-proof nets and conductive materials, etc.

Precision die cut solution for mobile phone industry

Fixture of many items such as window/len,mobilephone nameplate, O-ring and accessories of earphone/ microphone anti-dust mesh of Microphone, cable, keyboard, PCB, LCD reflective film/Light shielding card, LCD framework, Battery buffering pad, Battery door.

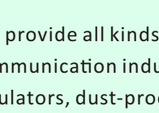

Co-Branding label

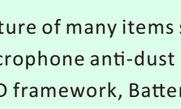

Information Lable


Ultra Destructible Warranty Lable


Lens Protection

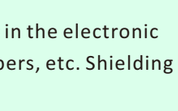
Display Window Mounting

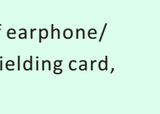

Earpiece /Speaker Cushion


LCD Reflection Foil /Lightguide


Earpiece /Speaker Mesh

Phone Tracing Labels

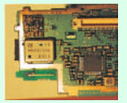

Display Gasket Mounting

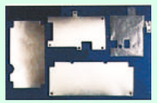

Display Dust Seal


EMI Conductive Foam


Backlight Components


Shock Absorbers

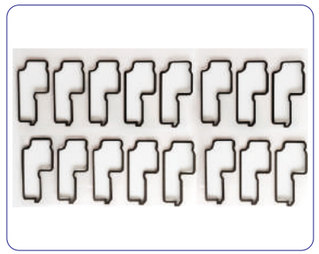

Chip Identification


Shielding & Insulation

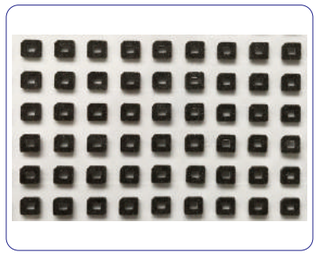
• Precise Die-Cutting

Solution for Electronics

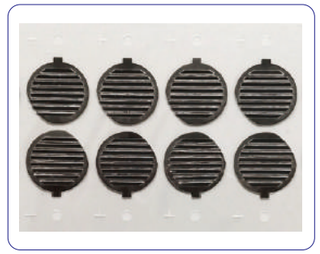
Used for fixing rubber parts, flash card, LCD buffering pad ,lens ,buffering pad, reflective film, battery plate and LCD module etc.



Foam



Battery buffering foam



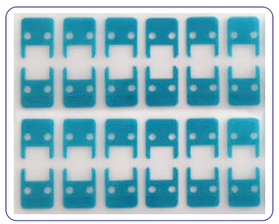
Loudspeaker anti-dust net



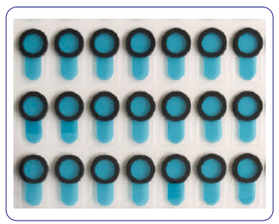
3M Double-side foam tape

Solution for Telecommunication

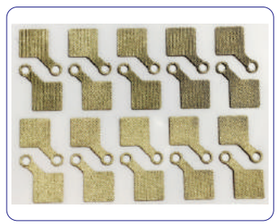
Used for fixing windows / lens, mobile phone nameplate, accessories of earphone /microphone, PCB, LCD reflective film / backlight, LCD frame, battery plate buffering pad.



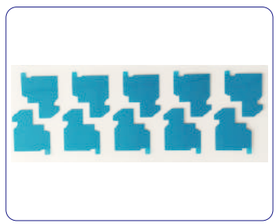
PCB back adhesive



Windows/lens



Conductive cloth



Graphite heat sink

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• Marketing network

KHJ has a perfect logistics system to ensure timely delivery of goods to customers. At the same time, KHJ has offices in many cities throughout the country to provide global customers.The most perfect hourly service and after-sales service.

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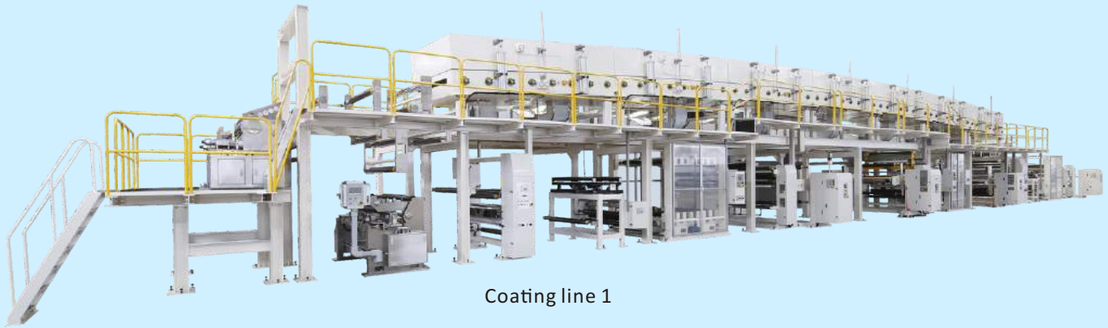
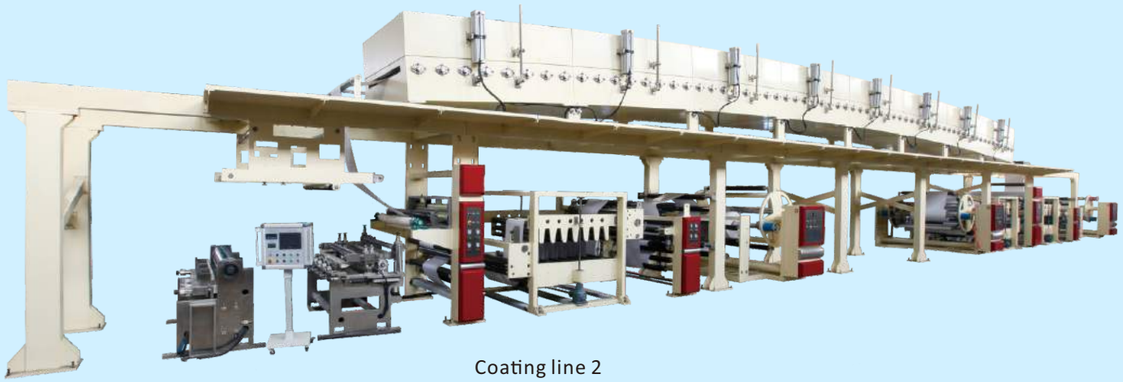
Shenzhen KHJ Technology Co., Ltd

Add: KHJ industrial park, Building 1,
Chuangxin industrial zone, Xintian community,
Guanlan, Longhua new district, Shenzhen, China
Tel : +86-755-82949965
Fax: +86-755-82949800

Factory equipments



Coating line 1



Coating line 2



Coating line 3









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Laboratory testing equipments



Thermal conductivity tester



Smart Electronics Tensile Tester



Automatic break strength testing machine



High and low temperature cycle tester



Ahesive holding tester



Constant temperature blast dryer



Salt spray tester



Normal temperature holding force testing machine



High temperature and high humidity tester



Research & Development

Chemical R&D expert team
Advanced chemical laboratories and comprehensive test equipments

ESD- Electro Static Discharge

1.An Introduction to ESD

Static electricity is an imbalance of electric charges within or on the surface of a material. The charge remains until it is able to move away by means of an electric current or electrical discharge. Static electricity is named in contrast with current electricity, which flows through wires or other conductors and transmits energy.

2.Cause

Static electricity is often generated through tribocharging, the separation of electric charges that occurs when two materials are brought into contact and then separated. Examples of tribocharging include walking on a rug, rubbing a plastic comb against dry hair, rubbing a balloon against a sweater, ascending from a fabric car seat, or removing some types of plastic packaging. In all these cases, the breaking of contact between two materials results in tribocharging, thus creating a difference of electrical potential that can lead to an ESD event.

Research & Development

Another cause of ESD damage is through electrostatic induction. This occurs when an electrically charged object is placed near a conductive object isolated from the ground. The presence of the charged object creates an electrostatic field that causes electrical charges on the surface of the other object to redistribute. Even though the net electrostatic charge of the object has not changed, it now has regions of excess positive and negative charges. An ESD event may occur when the object comes into contact with a conductive path. For example, charged regions on the surfaces of styrofoam cups or bags can induce potential on nearby ESD sensitive components via electrostatic induction and an ESD event may occur if the component is touched with a metallic tool.ESD can also be caused by energetic charged particles impinging on an object. This causes increasing surface and deep charging. This is a known hazard for most spacecraft.

3.Electrostatic discharge

Electrostatic discharge (ESD) is the sudden flow of electricity between two electrically charged objects caused by contact, an electrical short, or dielectric breakdown. The ESD occurs when differently-charged objects are brought close together or when the dielectric between them breaks down, often creating a visible spark.

ESD Damage—How Devices Fail
Electrostatic damage is defined as “change to an item caused by an electrostatic discharge that makes it fail to meet one or more specified parameters.” and can occur at any point from manufacture to field service. Typically, damage results from handling the devices in uncontrolled surroundings or when poor ESD control practices are used.

When an electronic device is exposed to an ESD event, it may no longer function. The ESD event may have caused a metal melt, junction breakdown, or oxide failure. The device's circuitry is permanently damaged causing the device to stop functioning totally or at least partially. Such failures usually can be detected when the device is tested before shipment. If a damaging level ESD event occurs after test, the part may go into production and the damage will go undetected until the device fails in final test.

Discharge to the Device
An ESD event can occur when any charged conductor (including the human body) discharges to an item. A cause of electrostatic damage could be the direct transfer of electrostatic charge from the human body or a charged material to the ESDS. When one walks across a floor, an electrostatic charge accumulates on the body. Simple contact (or close proximity) of a finger to the leads of an ESDS or assembly which is typically on a different electrical potential can allow the body to discharge, possibly causing ESD damage. The model used to simulate this event is the Human Body Model (HBM). A similar discharge can occur from a charged conductive object, such as a metallic tool or fixture. From the nature of the discharge, the model used to describe this event is known as the Machine Model (MM).

Discharge from the Device
The transfer of charge from an ESD to a conductor is also an ESD event. Static charge may accumulate on the ESDS itself through handling or contact and separation with packaging materials, work surfaces, or machine surfaces. This frequently occurs when a device moves across a surface or vibrates in a package. The model used to simulate the transfer of charge from an ESDS is referred to as the Charged Device Model (CDM). The capacitances, energies, and current waveforms involved are totally different from those of a discharge to the ESD sensitive item, resulting very likely in different failure modes.The trend towards automated assembly would seem to solve the problems of HBM ESD events. However, it has been shown that components may be more sensitive to damage when assembled by automated equipment. A device may become charged, for example, from sliding down the feeder. If it then contacts the insertion head or any other conductive surface, a rapid discharge occurs from the device to the metal object.

Field Induced Discharges

Another electrostatic charging process that can directly or indirectly damage devices is termed Field Induction. As noted earlier, whenever any object becomes electrostatically charged, there is an electrostatic field associated with that charge. If an ESDS is placed in that electrostatic field, a charge may be induced on the item. If the item is then grounded while within the electrostatic field, a transfer of charge from the device occurs as a CDM event. If the item is removed from the region of the electrostatic field and grounded again, a second CDM event will occur as the charge (of opposite polarity from the first event) is transferred from the device.

4.Types of ESD damage

There are basically two categories of damage from ESD:

a. Catastrophic damage
The electronic device is rendered inoperable immediately after the ESD event. A semiconductor junction or a connecting metallization could have been damaged by the electrostatic discharge.

b. Latent damage

The electronic device appears to be working fine following the ESD event. However, the sensitive circuitry has been damaged and could fail to operate properly at some time in the future.

5.Cost of ESD Damage

An ESD Association article highlights that losses in the electronics industry have been estimated to range anywhere from half a billion dollars to $5 billion.Independent consultants and corporate studies have found that ESD losses can be as high as 10% of annual revenues with an estimated aver-age negative impact of 6.5% of revenues.A typical high-tech OEM may be losing tens to hundreds of thousands of dollars annually to ESD damage, perhaps without knowing either the cause or the total impact. High-tech companies lose at least 4% to 6% of annual gross sales due to ESD every year.An OEM has much more to lose to static discharge than a component manufacturer, due to the cost of finished assemblies. A component that costs only $10 to replace and retest on its own could cost hundreds or thousands of dollars to repair or replace when it fails in the field. Estimates are that the cost of repairing an ESD damaged product increases tenfold at every level from component to system.





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• Some of our clients

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IMI · SANMINA · USI · NOKIA

HITACHI · Panasonic · SIEMENS · DELPHI

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